

DESCRIPTION

The SPN7002V is the N-Channel enhancement mode field effect transistors are produced using high cell density DMOS technology. These products have been designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance. They can be used in most applications requiring up to 300mA DC and can deliver pulsed currents up to 1.0A. These products are particularly suited for low voltage, low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.

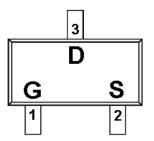
APPLICATIONS

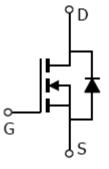
- Drivers: Relays, Solenoids, Lamps, Hammers, Display, Memories, Transistors, etc.
- High saturation current capability. Direct Logic-Level Interface: TTL/CMOS
- Battery Operated Systems
- Solid-State Relays

FEATURES

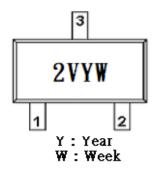
- \bullet 60V/0.50A, RDS(ON)=4.0 Ω @VGS=10V
- 60V/0.30A, RDS(ON)= 5.0Ω @VGS=5V
- Super high density cell design for extremely low RDS (ON)
- Exceptional on-resistance and maximum DC current capability
- ♦ SOT-523 (SC-89) package design

PIN CONFIGURATION (SOT-523 / SC-89)





PART MARKING



PIN DESCRIPTION					
Pin	Symbol	Description			
1	G	Gate			
2	S	Source			
3	D	Drain			

ORDERING INFORMATION

Part Number	Package	Part Marking
SPN7002VS52RGB	SOT-523	2VYW

[※] SPN7002VS52RGB : Tape Reel ; Pb − Free; Halogen − Free

ABSOULTE MAXIMUM RATINGS (Ta=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit	
Drain-Source Voltage		VDSS	60	V
Gate –Source Voltage - Continuous		VGSS	±20	V
Gate –Source Voltage - Non Repetitive (t _p < 50μs)		VGSS	±40	V
Continuous Drain Current(TJ=150°C)		ID	0.35	A
Pulsed Drain Current (*)		Ірм	1.0	A
Power Dissipation	Ta=25°C	PD	0.15	W
Operating Junction Temperature		Тл	-55 ~ 150	°C
Storage Temperature Range		Tstg	-55 ~ 150	°C
Thermal Resistance-Junction to Ambient		RθJA	830	°C/W

^(*) Pulse width limited by safe operating area

Parameter	Symbol	Conditions	Min.	Тур	Max.	Unit	
11 11 111	Symbol	Conditions	WIIII.	Тур	wiax.	Omt	
Static							
Drain-Source Breakdown Voltage	V(BR)DSS	VGS=0V,ID=250uA	60			V	
Gate Threshold Voltage	VGS(th)	VDS=VGS,ID=250uA	1.0	1.7	2.5] '	
Gate Leakage Current	Igss	$V_{DS}=0V,V_{GS}=\pm20V$			±100	nA	
		VDS=48V,VGS=0V			1	uA	
Zero Gate Voltage Drain Current	Idss	Vds=48V,Vgs=0V Tj=55°C			10		
Drain-Source On-Resistance	RDS(on)	Vgs=10V,Id=0.50A			4.0	Ω	
	` ′	Vgs= 5V,Id=0.30A			5.0		
Source-drain Current Source-drain Current (pulsed)	Isd Isdm (2)				0.12 0.85	A	
Forward Transconductance	Gfs(1)	$V_{DS} = 10 \text{ V}, I_{D} = 0.5 \text{ A}$		0.6	0.03	S	
Diode Forward Voltage	VsD(1)	$V_{GS} = 0 \text{ V, Is} = 0.12A$		0.85	1.5	V	
Dynamic	•						
Total Gate Charge	Qg			1.4	2.0	nC	
Gate-Source Charge	Qgs	VDD=30V, ID=1A, VGS=5V		0.8			
Gate-Drain Charge	Qgd	- v Gs-3 v		0.5		1	
Input Capacitance	Ciss			43	60		
Output Capacitance	Coss	V _{DS} =25V, f=1MHz, V _{GS} =0		20	30	pF	
Reverse Transfer Capacitance	Crss	- V US-0		6	10		
	td(on)			5	20	ns	
Turn-On Time	tr	VDD=30V, ID=0.5A		15			
The control of the co	td(off)	$RG=4.7\Omega$, $VGS=4.5V$		7	20		
Turn-Off Time	tf			8			

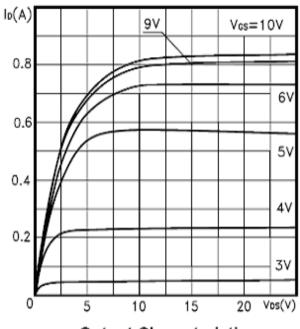
⁽¹⁾ Pulsed: Pulse duration = $300 \mu s$, duty cycle 1.5 %.

⁽²⁾ Pulse width limited by safe operating area.

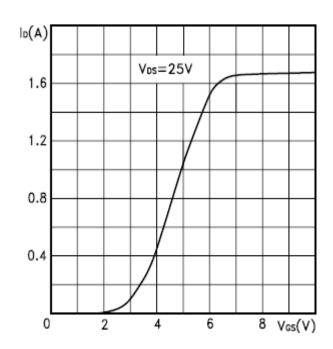


N-Channel Enhancement Mode MOSFET

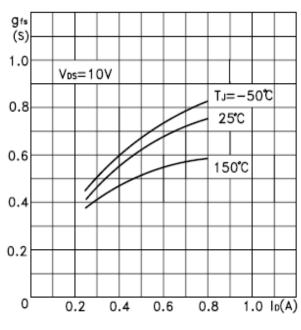
TYPICAL CHARACTERISTICS



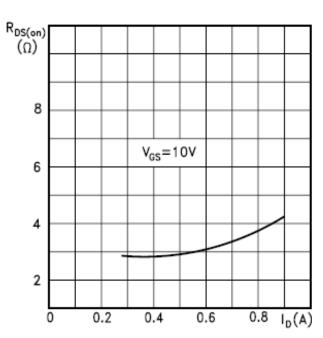
Output Characteristics



Transfer Characteristics



Transconductance

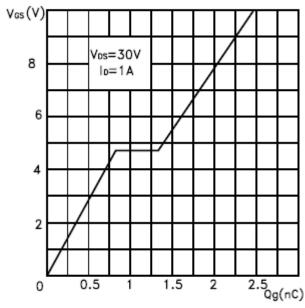


Static Drain-source On Resistance

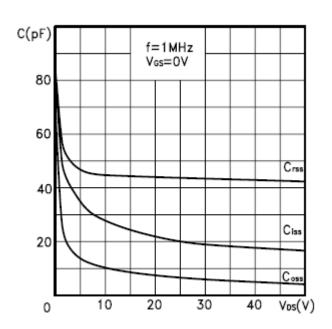


N-Channel Enhancement Mode MOSFET

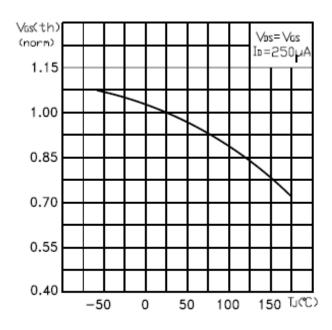
TYPICAL CHARACTERISTICS



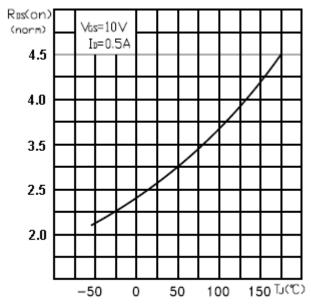
Gate Charge vs Gate-source Voltage



Capacitance Variations



Normalized Gate Threshold Voltage vs Temperature

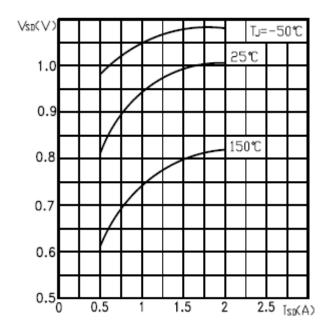


Normalized On Resistance vs Temperature

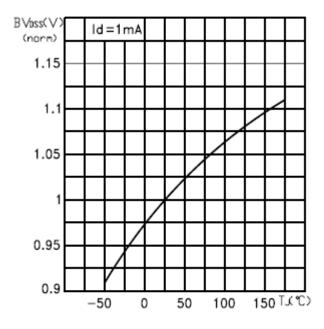


N-Channel Enhancement Mode MOSFET

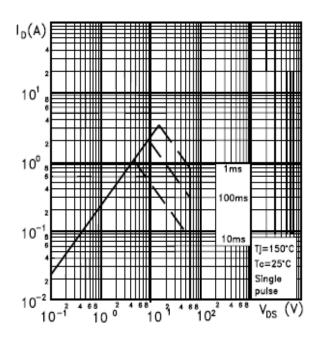
TYPICAL CHARACTERISTICS



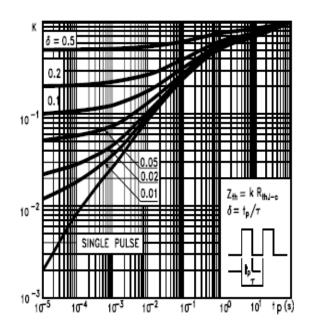
Source-Drain Forward



Normalized BVDSS vs Temperature

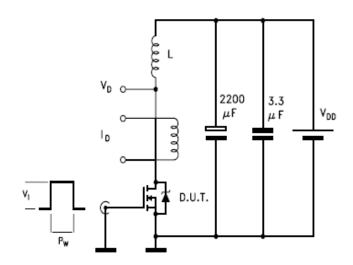


Safe Operating Area



Thermal Impedance

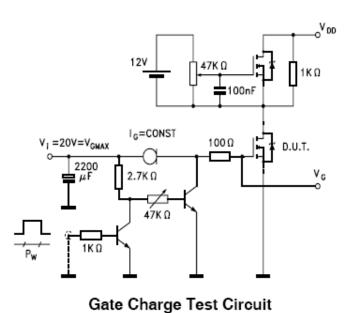
TYPICAL TESTING CIRCUIT

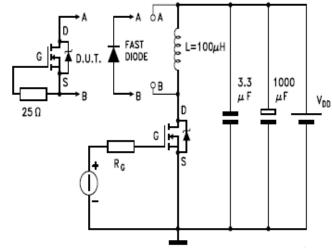


R_L 2200 3.3 μF V_{DD} V_S R_G D.U.T.

Unclamped Inductive Load Test

Switching Times Test Circuit

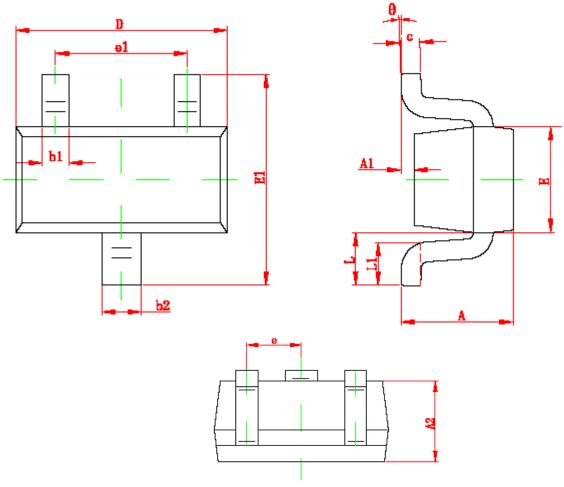




Test Circuit For Inductive Load Switching and Diode Recovery Times



SOT-523 PACKAGE OUTLINE



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
Α	0.700	0.900	0.028	0.035	
A1	0.000	0.100	0.000	0.004	
A2	0.700	0.800	0.028	0.031	
b1	0.150	0.250	0.006	0.010	
b2	0.250	0.325	0.010	0.013	
С	0.100	0.200	0.004	0.008	
D	1.500	1.700	0.059	0.067	
Е	0.750	0.850	0.030	0.033	
E1	1.450	1.750	0.057	0.069	
е	0.500 TYP		0.020 TYP		
e1	0.900	1.100	0.035	0.043	
L	0.550 REF		0.022 REF		
L1	0.280	0.440	0.011	0.017	
θ	0°	4°	0°	4°	

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